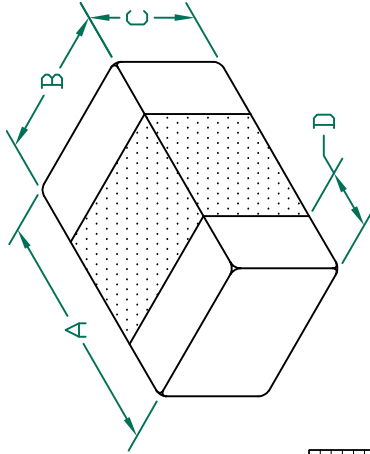
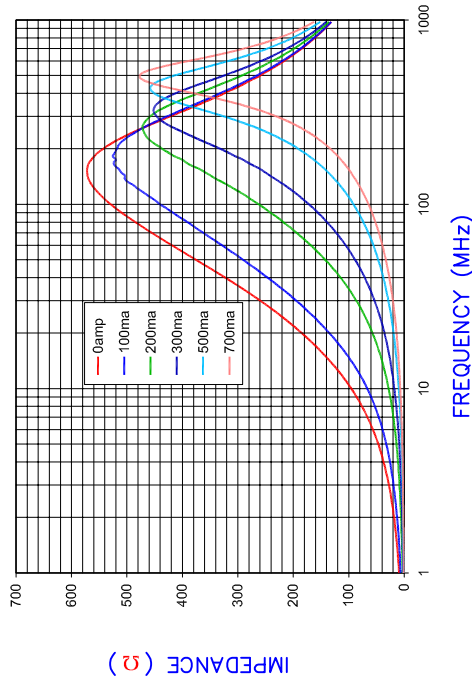


PHYSICAL DIMENSIONS:

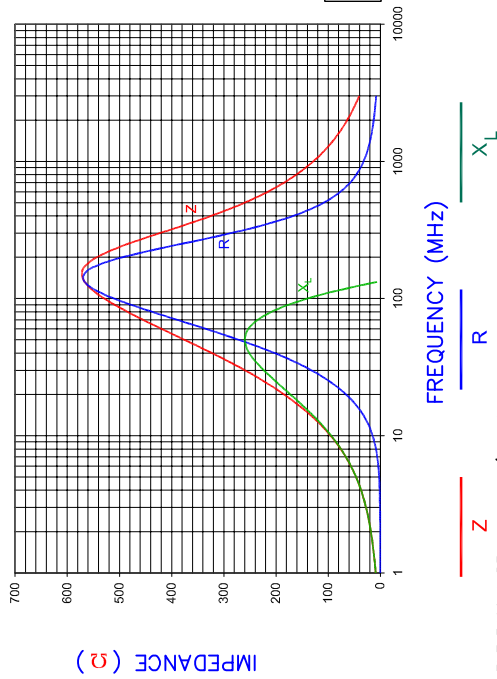
A	2.00	[.079]	± 0.20	[.008]
B	1.25	[.049]	± 0.20	[.008]
C	0.85	[.033]	± 0.20	[.008]
D	0.51	[.020]	± 0.25	[.010]



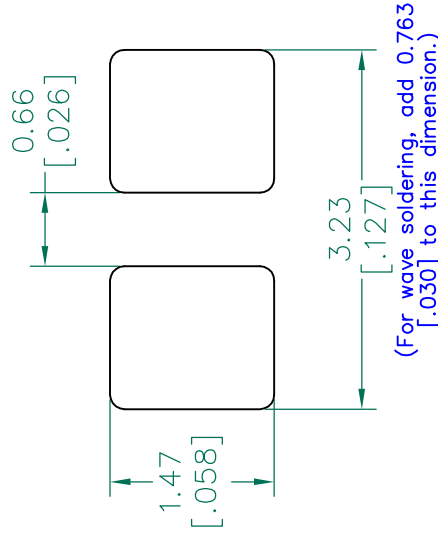
Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



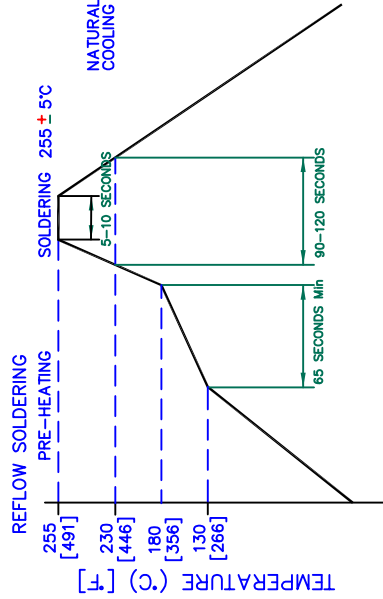
[Z] , R, AND X vs. FREQUENCY



LAND PATTERNS FOR REFLOW SOLDERING



RECOMMENDED SOLDERING CONDITIONS



ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	470	
Minimum	353	
Maximum	588	700 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMP. RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)



DIMENSIONS ARE IN mm [INCHES].

This print is the property of Laird Tech. and is loaned in confidence and subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	
REV	PROJECT/PART NUMBER
D	HZ0805G471R-10
ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13 QU
CHANGE TO PAPER TAPE	03/03/10 JUN
UPDATE COMPANY LOGO ADD ROHS	03/24/08 JPK
ORIGINAL DRAFT	04/03/04 TMB
DESCRIPTION	DATE



REV	PART TYPE	REV	SCALE	DATE	DATE	DATE	DATE	DATE	DATE
D	CO-FIRE	D	NTS	04/03/04	04/03/04	04/03/04	04/03/04	04/03/04	04/03/04
DRAWN BY:		TMB		SHEET:		2 of 2			